

注記 NOTES

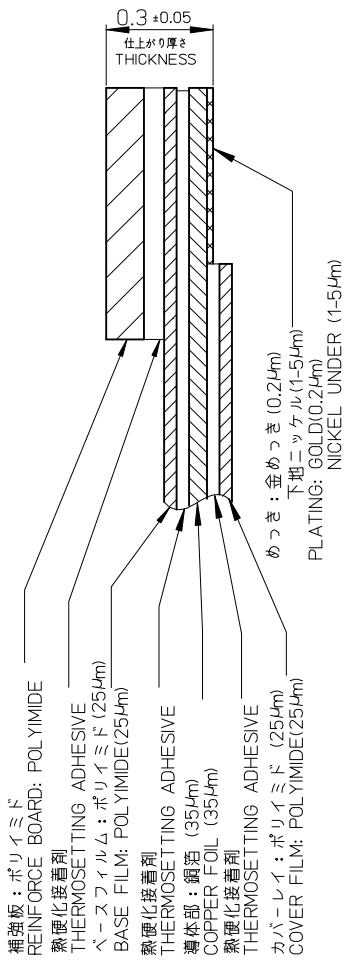
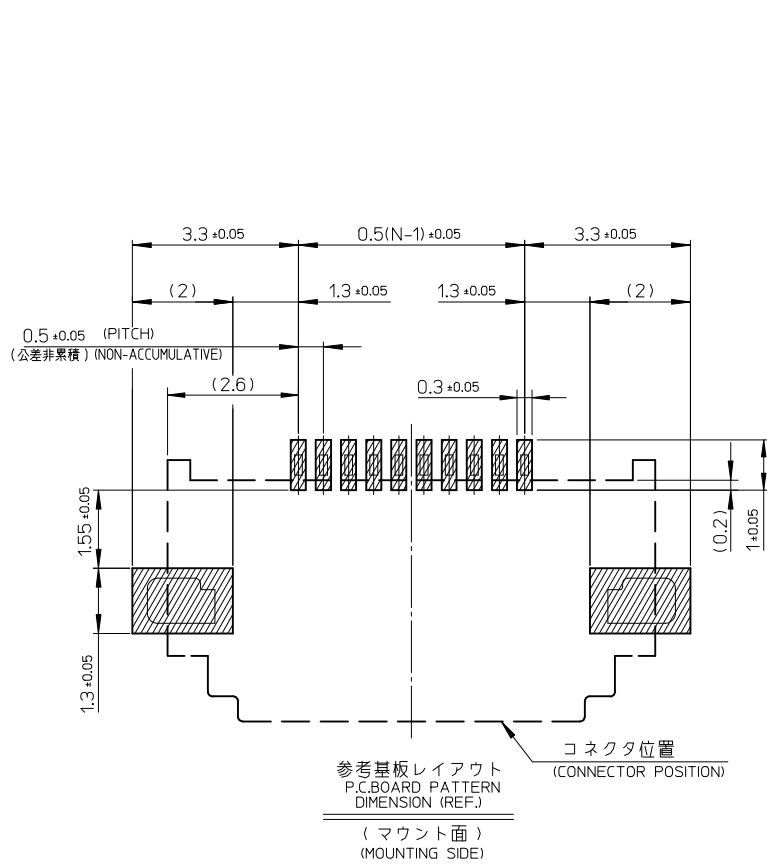
1. 使用材料 MATERIAL
 ハウジング : 液晶ポリマー ガラス充填, UL94-V0(ベージュ)
 HOUSING : LIQUID CRYSTAL POLYMER GLASS FILLED, UL94V-0(BEIGE)
 アクチュエータ : PPS ガラス充填, UL94-V0(黒)
 ACTUATOR : PPS GLASS FILLED, UL94V-0(BLACK)
 ターミナル : リン青銅(t=0.15)
 TERMINAL : PHOSPHOR BRONZE
 金具 : リン青銅(t=0.15)
 FITTING NAIL : PHOSPHOR BRONZE
2. めっき仕様 PLATING
 ターミナル TERMINAL
 コンタクト部: 部分金めっき (0.05 μm以上)
 テール部: 部分金めっき
 下地: ニッケルめっき (1.0 μm以上)
 CONTACT AREA : SEPARATED GOLD PLATING (0.05 MICROMETER MINIMUM)
 SOLDER TAIL AREA : SEPARATED GOLD PLATING
 UNDERPLATE : NICKEL OVERALL (1.0 MICROMETER MINIMUM)
 金具 FITTING NAIL
 鍍めっき (1.0 μm以上)
 下地: ニッケルめっき (1.0 μm以上)
 TIN PLATING (1.0 MICROMETER MIN.)
 UNDER PLATING : NICKEL PLATING (1.0 MICROMETER MIN.)
3. エンボスタープ梱包時は、アクチュエータが開いた状態とする。
 IN THE PACKAGE, ACTUATOR OF PART 502790-**11 SHOULD BE CLOSED.

4. パターン剥離止め用金具
 FITTING NAIL FOR PREVENTION OF PEELING OF P.C.B. PATTERN.
 R0.3は、FPC導体部にかからないこと。
 R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
5. R0.3は、FPC導体部にかからないこと。
 R0.3 MUST NOT BE OVERLAPPED TO PATTERN OF FPC.
6. N: 極数 N: CIRCUIT.
7. ELV及びRoHS適合品
 ELV AND ROHS COMPLIANT
8. テールと金具を併せた平坦度は0.1mm以下とする。
 TAILS AND NAILS COPLANALITY TO BE 0.1mm MAX.

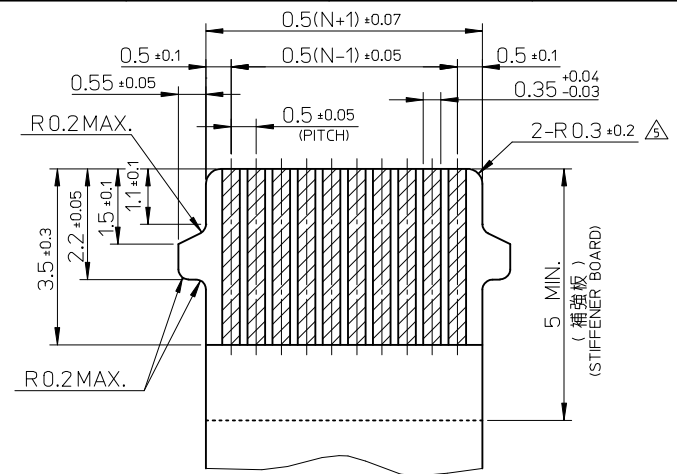
43.1	39.5	44.7	502790-8091	80
35.1	31.5	36.7	502790-6491	64
33.1	29.5	34.7	502790-6091	60
28.1	24.5	29.7	502790-5091	50
23.1	19.5	24.7	502790-4091	40
18.1	14.5	19.7	502790-3091	30
C	B	A	EMBOSSED PACKAGE	CIRCUIT
オーダー番号 ORDER No.				

CONNECTOR SERIES No. 502790-**11

REVISED EC NO: J2009-2576 DRWN: TAKASAKI 2009/05/28 CHKD: HAYASHI 2009/05/28 APPR: NUKITA 2009/05/28	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	DRAWN BY YTAKAYASU	DATE 2007/08/10	TITLE 0.5 FPC CONN. ZIF E/O 2 CONTACTS TYPE HSG ASS'Y (H=2.5)				
		10 OVER 30 UNDER	± ---	CHECKED BY KTAKAHASHI	DATE 2007/08/10	MOLEX INCORPORATED				
		30 OVER	± ---	APPROVED BY HHRATA	DATE 2007/08/10	DOCUMENT NO. 502790-**11				
C	REV	ANGULAR ± --- ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		SHEET NO. 1 OF 2				



FPC構成推奨仕様
STRUCTURE OF FPC

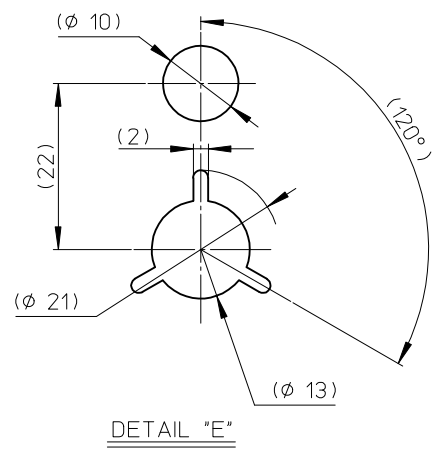
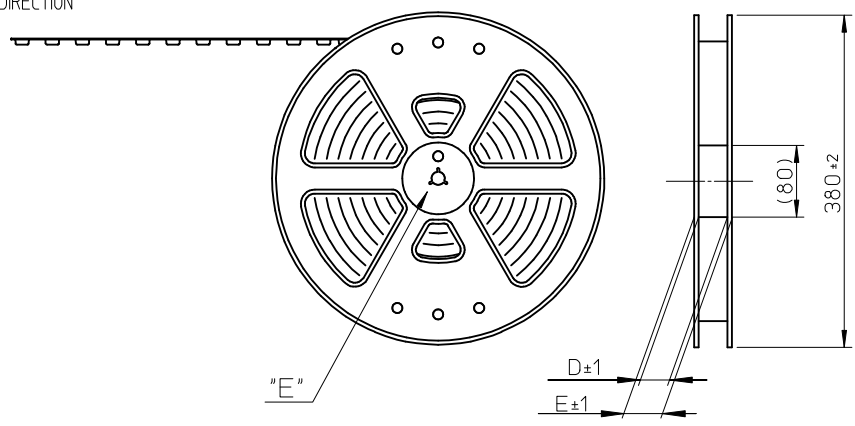


FPC について:
 打ち抜き方向は導体側から補強板側を推奨します。
 導体部については軟銅箔35µmまたは50µmを推奨します。
 補強フィルム材質はポリイミドを推奨します。ベースフィルムは25µmを推奨します。
 接着剤は熱硬化接着剤を推奨します。
 尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様お願い致します。

ABOUT FPC
 RECOMMENDED PUNCHER DIRECTION : FROM CONDUCTOR SIDE TO STIFFENER FILM SIDE.
 RECOMMENDED CONDUCTOR SPEC :
 THICKNESS OF SOFT COPPER FOIL : 35 MICROMETER OR 50 MICROMETER.
 RECOMMENDED MATERIAL/THICKNESS.
 STIFFENER FILM : POLYIMIDE
 BASE FILM THICKNESS : 25µm
 BONDING AGENT : THERMOSETTING BONDING AGENT
 PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

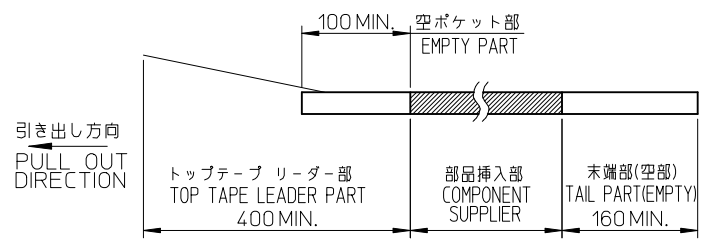
SEE SHEET 1 OF 2 EC NO: J2009-2576 DRWN:MTAKASAKI 2009/05/25 CHKD:HAYASHI 2009/05/28 APPR:NUKITA 2009/05/28	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± ---	DRAWN BY YTAKAYASU	DATE 2007/08/10	TITLE 0.5 FPC CONN. ZIF E/O 2 CONTACTS TYPE HSG ASS'Y (H=2.5)		
	10 OVER 30 UNDER	± ---	CHECKED BY KTAHASHI	DATE 2007/08/10	MOLEX INCORPORATED		
	30 OVER	± ---	APPROVED BY HHIRATA	DATE 2007/08/10	MATERIAL NO. 502790-***11	DOCUMENT NO. SD-502790-001	SHEET NO. 2 OF 2
ANGULAR	± --- °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

引き出し方向
PULL OUT DIRECTION



NOTES

1. 梱包数量 : 2000個/リール
NUMBER OF CONNECTORS : 2000PIECES/REEL
2. リードテープ長さ
LEAD TAPE LENGTH



3. 製品詳細寸法については図面 SD-502790-001を参照下さい。
FOR DIMENSIONS OF PRODUCT, REFER TO SD-502790-001.

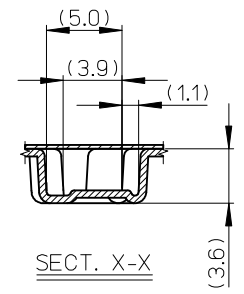
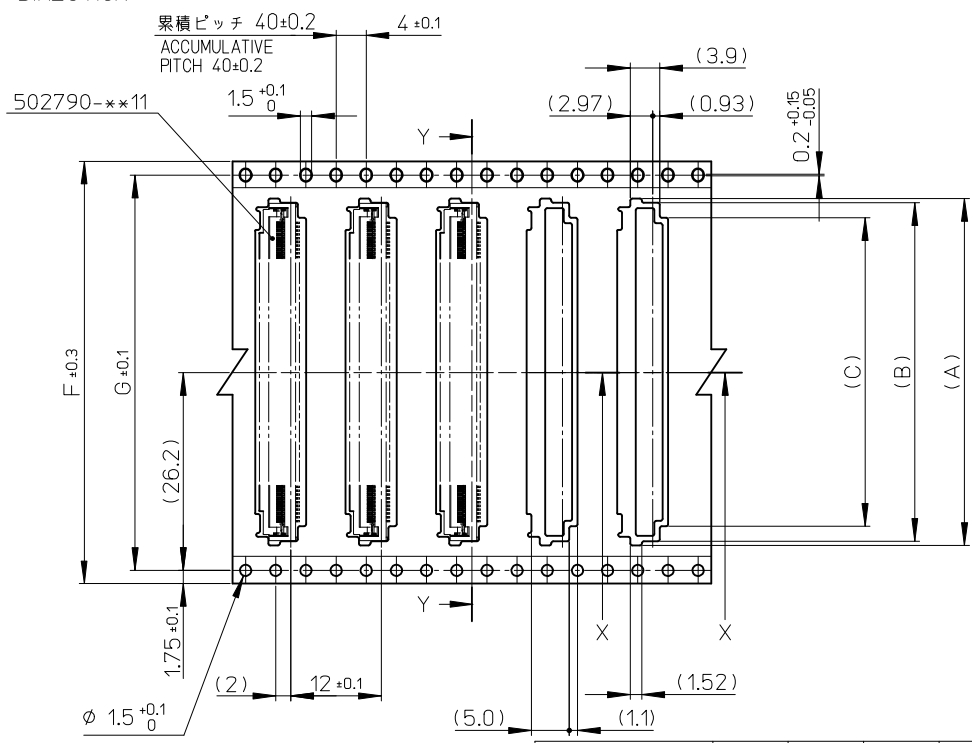
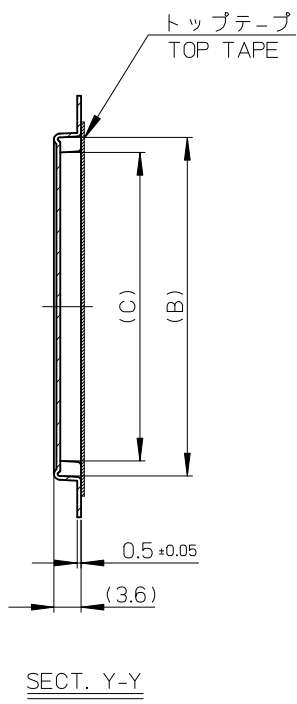
4. 材料 MATERIAL
 キャリアテープ : ポリスチレン
 CARRIER TAPE : POLYSTYRENE
 トップテープ : ポリエチレンテレフタレート, ポリエチレン
 TOP TAPE : POLYETHYLENE TEREPHTHALATE , POLYETHYLENE
 リール : ポリスチレン<リサイクル材を含む>
 REEL : POLYSTYRENE<RECYCLE MATERIAL CONTAINED>

5. ELV及びRoHS適合品 ELV AND RoHS COMPLIANT

REVISED EC NO: J2009-2322 DR: MNTAKASAKI 2009/04/20 CH: D:MHAYASHI 2009/04/20 APPR: NUKITA 2009/04/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE --	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±---	DRAWN BY YTAKAYASU	DATE 2007/11/05	TITLE 0.5 FPC CONN ZIF E/O 2 CONTACTS TYPE EMBSTP PACKAGE (H=2.5)			
	10 OVER 30 UNDER	±---	CHECKED BY KTAKAHASHI	DATE 2007/11/05	MOLEX MOLEX INCORPORATED			
	30 OVER	±---	APPROVED BY HHRATA	DATE 2007/11/05	MATERIAL NO. 502790-***91	DOCUMENT NO. SD-502790-002	SHEET NO. 1 OF 2	
	ANGULAR ±--- ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

10 9 8 7 6 5 4 3 2 1

引き出し方向
PULL OUT
DIRECTION



56	52.4	56	61.4	57.4	40.9	44.9	46	502790-8091	80
	52.4	56	61.4	57.4	32.9	36.9	38	502790-6491	64
	52.4	56	61.4	57.4	30.9	34.9	36	502790-6091	60
44	40.4	44	49.4	45.4	25.9	29.9	31	502790-5091	50
	40.4	44	49.4	45.4	20.9	24.9	26	502790-4091	40
32	28.4	32	37.4	33.4	15.9	19.9	21	502790-3091	30
キャリアテープ幅 CARRIER TAPE WIDTH	G	F	E	D	C	B	A	製品番号 MATERIAL NO.	極数 CIRCUIT

SEE SHEET 1 OF 2 EC NO.: J2009-2322 DRWN: TAKASAKI 2009/04/20 CHKD: HAYASHI 2009/04/20 APPR: NUKITA 2009/04/21	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE --	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	± ---	DRAWN BY YTAKAYASU	DATE 2007/11/05	TITLE 0.5 FPC CONN ZIF E/O 2 CONTACTS TYPE EMBSTP PACKAGE (H=2.5)			
	10 OVER 30 UNDER	± ---	CHECKED BY KTAKAHASHI	DATE 2007/11/05	MOLEX INCORPORATED			
	30 OVER	± ---	APPROVED BY HHRATA	DATE 2007/11/05	DOCUMENT NO. SD-502790-002		SHEET NO. 2 OF 2	
	ANGULAR ± --- °		MATERIAL NO. 502790-***91		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS								